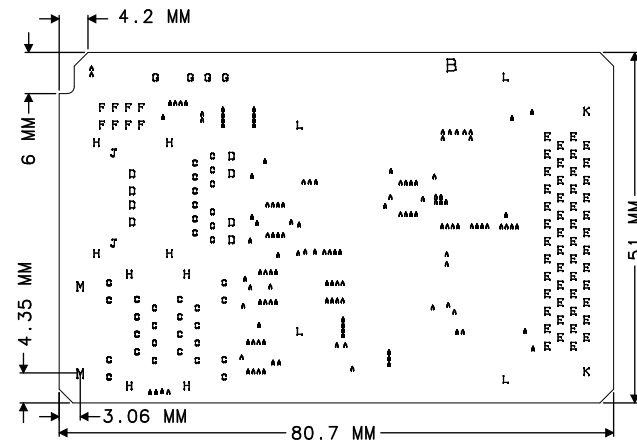




PARAMETERS FOR PCB MANUFACTURING

- 1.0 FOLLOW MELLANOX SOW. IN CASE OF CONFLICT REFER TO THE FAB NOTES BELOW.
- 2.0 ARTWORK SUPPLIED MARKED , PCB000760 NO OF LAYERS: 04
- 3.0 SPEC: IPC 6012 Class 2, 6016, IPC 600 Class 2, IPC-TM-650
- 4.0 FOR HOLES DIAMETER, PLATING AND SYMBOLS SEE DRILL TABLE.
DIAMETER SPECIFIED IN DRILL TABLE ARE FOR THE FINISHED PCB (AFTER ALL PLATING PROCESS).
- 5.0 DIMENSIONS: SEE MECHANICAL OUTLINE
THE TOLERANCE FOR THE MECHANICAL DIMENSIONS SHALL BE +/-0.127MM
- 6.0 SEE PAGE 2 FOR STACKUP DEFINITIONS
- 7.0 SOLDERMASK: PHOTOIMAGEBLE PER IPC-SM-840. MAT FINISH. COLOR GREEN
- 8.0 PLUGGING - PLUGGING SHOULD BE IMPLEMENTED ON THE C.S. USING ATTACHED ARTWORK
- 9.0 FINISH: IMMERSION SILVER PER IPC 4553. FINISH THICKNESS: 0.2-0.3 UM RECOMMENDED, 0.12 UM MINIMUM
- 10.0 SILKSCREEN PRINTING IN WHITE EPOXY INK ON TOP SIDE ONLY
NO SMEARING OR COVERED PADS ALLOWED

Through Holes
All Drills (unless specified) +/- 0.05 (MM)

Symbol	Diameter	Tolerance	Plated	Quantity	Comments
A	0.25	+0.05 / -0.25	Yes	138	
B	0.56	+/- 0.05	Yes	1	
C	0.89	+/- 0.05	Yes	36	
D	0.97	+/- 0.08	Yes	8	
E	1.00	+/- 0.05	Yes	50	
F	1.02	+/- 0.05	Yes	8	
G	1.09	+/- 0.05	Yes	4	
H	1.57	+/- 0.05	Yes	8	
J	2.31	+/- 0.08	Yes	2	
K	2.60	+/- 0.10	Yes	2	
L	3.20	+/- 0.10	Yes	4	
M	3.25	+/- 0.05	No	2	

APPROVALS

DRAWN ALEXANDERS	DATE 18.12.13
CHECKED	DATE
APPROVED	DATE

MELLANOX TECHNOLOGIES LTD.

FABRICATION DRAWING
PCB000760

SIZE A3	CAGE CODE	DWG NO. PCB000760	REV 00
SCALE 1.0 = 1.0		SHEET 1 OF 1	

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Fax: +972-4-959-3245

Date:	11/19/2013
P/N:	PCB000760
Layers:	4
Total Thickness:	1.6mm±10%
Finish:	Immersion silver

Stack-up and impedance requirements

Material:	FR4-High TG
Panel size and PCB units per Panel	51.0mm X 80.7MM ; Two units per array
PCB Utilization (%)	
Gold finger:	No
Back drill depth/width types on CS:	0
Back drill depth/width types on PS:	0



All dimensions are in mils unless otherwise stated

Layer	Copper parameters				Resin parameters				Impedance parameters							
	signal/ Power/ GND	Copper weight [oz]	Copper thickness after plaiting [Mil]	Copper roughness	Dielectric thickness	Material	Glass type	Resin content [%]	Differential pairs parameters				SE signal parameters			
									Imp. [Ω]	Default		Neck-down		Imp.[Ω]	Default Width	Neck-down Width
										Width	Space	Width	Space			
Layer 1 - CS	Signal	0.5 oz	2.1						95±10%	6.1	7.9	NA	NA	50±10%	7.8	NA
Prepreg					5	FR4-HIGH TG	EM827 2116X1									
Layer 2	GND	1 oz	1.2						NO CONTROLLED IMPEDANCE							
Core					45	FR4-HIGH TG	EM827 45MIL CORE									
Layer 3	Signal	1 oz	1.2						95±10%	4.8	9.2	NA	NA	50±10%	5.6	NA
Prepreg					4.4	FR4-HIGH TG	EM827 2116X1									
Layer 4 - PS	GND	0.5 oz	2.1						NO CONTROLLED IMPEDANCE							

If you have any queries please do not hesitate to contact:

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Revision control:		
Revision	Date	Description
00	11/19/2013	Final Release

Notes:	
1	Impedance controlled differential pairs widths are defined with two digits after the decimal points inside the gerbers. Eg 9 mil width is defined as 8.99.
2	The dialectric thickness, line widths and differential space values are nominal values. Minor changes can be done to meet the impedance requirements.(HW designer approval is a must)
3	Trace widths are nominal finished dimensions.